PECL DIGITAL VIDEO CLOCK SOURCE

ICS664-04

Description

The ICS664-04 provides clock generation and conversion for clock rates commonly needed in HDTV digital video equipment. The ICS664-04 uses the latest Phase-Locked Loop (PLL) technology to provide excellent phase noise and long-term jitter performance for superior synchronization and S/N ratio.

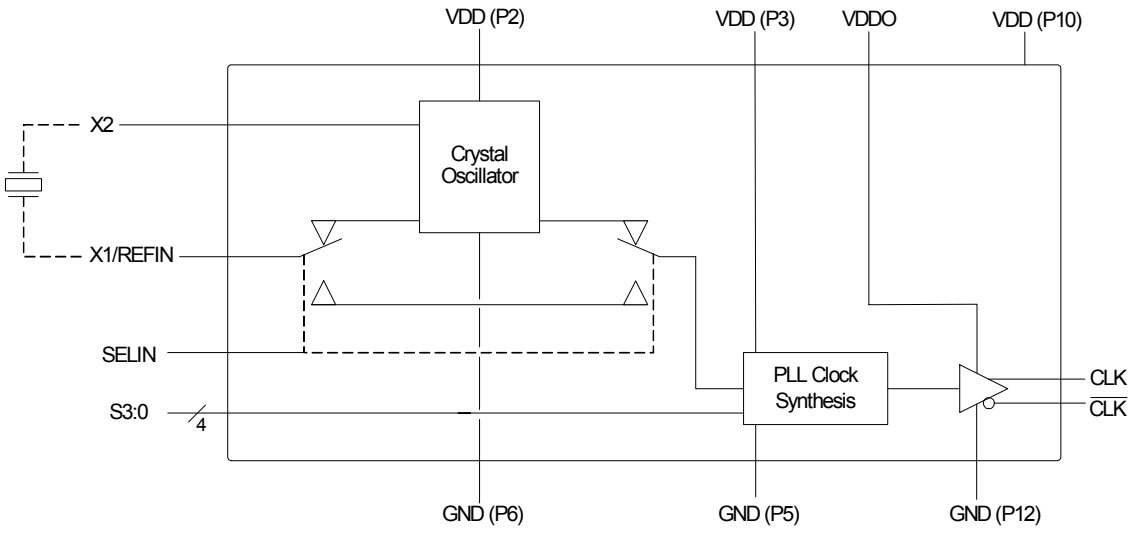
For audio sampling clocks generated from 27 MHz, use the ICS661.

Please contact IDT if you have a requirement for an input and output frequency not included in this document. IDT can rapidly modify this product to meet special requirements.

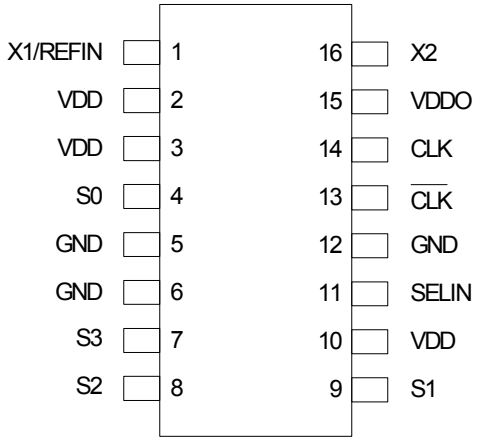
Features

- Packaged in 16-pin TSSOP
- Available in Pb (lead) free package
- Clock or crystal input
- Low phase noise
- Low jitter
- Exact (0 ppm) multiplication ratios
- Power-down control
- Improved phase noise over ICS660
- Differential outputs

Block Diagram



Pin Assignment



16-pin 4.40 mil body, 0.65 mm pitch TSSOP

Output Clock Selection Table

S3	S2	S1	S0	Input Frequency (MHz)	Output Frequency (MHz)
0	0	0	0		Outputs disabled
0	0	0	1	27	27
0	0	1	0	27	74.25
0	0	1	1	27	74.$\overline{175824}$
0	1	0	0	27	67.5
0	1	0	1	67.5	27
0	1	1	0	27	148.5000
0	1	1	1	27	148.351648
1	0	0	0	74.25	54
1	0	0	1	74.$\overline{175824}$	54
1	0	1	0	74.25	27
1	0	1	1	74.$\overline{175824}$	27
1	1	0	0	54	74.25
1	1	0	1	54	74.$\overline{175824}$
1	1	1	0	54	148.5
1	1	1	1	54	148.351648

Pin Descriptions

Pin Number	Pin Name	Pin Type	Pin Description
1	X1/REFIN	Input	Connect this pin to a crystal or clock input.
2	VDD	Power	Power supply. Connect to 3.3 V.
3	VDD	Power	Power supply. Connect to 3.3 V.
4	S0	Input	Output frequency selection. Determines output frequency per table above. On chip pull-up.
5	GND	Power	Connect to ground.
6	GND	Power	Connect to ground.
7	S3	Input	Output frequency selection. Determines output frequency per table above. On chip pull-up.
8	S2	Input	Output frequency selection. Determines output frequency per table above. On chip pull-up.
9	S1	Input	Output frequency selection. Determines output frequency per table above. On chip pull-up.
10	VDD	Power	Power supply. Connect to 3.3 V.
11	SELIN	Input	Low for clock input, high for crystal. On chip pull-up.
12	GND	Power	Connect to ground.
13	$\overline{\text{CLK}}$	Output	Complimentary clock output.
14	CLK	Output	Clock output.
15	VDDO	Power	Power supply. Connect to 3.3 V.
16	X2	Input	Connect this pin to a crystal. Leave open if using a clock input.

Application Information

Termination Resistor

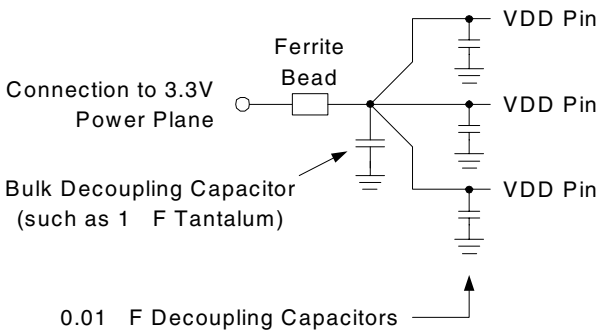
Terminate the outputs with 50Ω to ground.

Decoupling Capacitors

As with any high-performance mixed-signal IC, the ICS664-04 must be isolated from system power supply noise to perform optimally.

Decoupling capacitors of 0.01µF must be connected between each VDD and the PCB ground plane. To further guard against interfering system supply noise, the ICS664-04 should use one common connection to the PCB power plane as shown in the diagram on the next page. The ferrite bead and bulk capacitor help reduce lower frequency noise in the supply that can lead to output clock phase modulation.

Recommended Power Supply Connection for Optimal Device Performance



All power supply pins must be connected to the same voltage, except VDDO, which may be connected to a lower voltage in order to change the output level.

To achieve the absolute minimum jitter, power the part with a dedicated LDO regulator, which will provide high isolation from power supply noise. Many companies produce very small, inexpensive regulators; an example is the National Semiconductor LP2985.

Crystal Load Capacitors

If a crystal is used, the device crystal connections should include pads for capacitors from X1 to ground and from X2 to ground. These capacitors are used to adjust the stray capacitance of the board to match the nominally required crystal load capacitance. To reduce possible noise pickup, use very short PCB traces (and no vias) been the crystal and device.

The value of the load capacitors can be roughly determined by the formula $C = 2(C_L - 6)$ where C is the load capacitor connected to X1 and X2, and C_L is the specified value of the load capacitance for the crystal. A typical crystal C_L is 18 pF, so $C = 2(18 - 6) = 24$ pF. Because these capacitors adjust the stray capacitance of the PCB, check the output frequency using your final layout to see if the value of C should be changed.

PCB Layout Recommendations

For optimum device performance and lowest output phase noise, the following guidelines should be observed.

1) Each 0.01µF decoupling capacitor should be mounted on the component side of the board as close to the VDD pin as possible. No vias should be used between decoupling capacitor and VDD pin. The PCB trace to VDD pin should be kept as short as possible, as should the PCB trace to the ground via. Distance of the ferrite bead and bulk decoupling from the device is less critical.

2) The external crystal should be mounted next to the device with short traces. The X1 and X2 traces should not be routed next to each other with minimum spaces, instead they should be separated and away from other traces.

3) To minimize EMI, and obtain the best signal integrity, the 50Ω series termination resistor should be placed close to the clock output.

4) An optimum layout is one with all components on the same side of the board, minimizing vias through other signal layers (the ferrite bead and bulk decoupling capacitor can be mounted on the back). Other signal traces should be routed away from the ICS664-04. This includes signal traces just underneath the device, or on layers adjacent to the ground plane layer used by the device.

Absolute Maximum Ratings

Stresses above the ratings listed below can cause permanent damage to the ICS664-04. These ratings, which are standard values for IDT commercially rated parts, are stress ratings only. Functional operation of the device at these or any other conditions above those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods can affect product reliability. Electrical parameters are guaranteed only over the recommended operating temperature range.

Item	Rating
Supply Voltage, VDD	5.5 V
All Inputs and Outputs	-0.5V to VDD+0.5 V
Ambient Operating Temperature	0 to +70° C
Storage Temperature	-65 to +150° C
Junction Temperature	125° C
Soldering Temperature	260° C

Recommended Operation Conditions

Parameter	Min.	Typ.	Max.	Units
Ambient Operating Temperature	0		+70	°C
Power Supply Voltage (measured in respect to GND)	+3.135		+3.465	V

DC Electrical Characteristics

Unless stated otherwise, **VDD = VDDO = 3.3 V ±5%**, Ambient Temperature 0 to +70° C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Operating Voltage	VDD		3.135	3.3	3.465	V
	VDDO		3.135	3.3	3.465	V
Supply Current	IDD	No Load		40		mA
Standby Supply Current	IDDPD			450		µA
Input High Voltage	V_{IH}		2			V
Input Low Voltage	V_{IL}				0.8	V
Output High Voltage	V_{OH}		VDD-1.7		VDD-1.2	V
Output Low Voltage	V_{OL}		VDD-2.3		VDD-1.8	V
Input Capacitance	C_{IN}	Input pins		7		pF
Internal Pull-up Resistor	R_{PU}	Input pins		120		kΩ

AC Electrical Characteristics

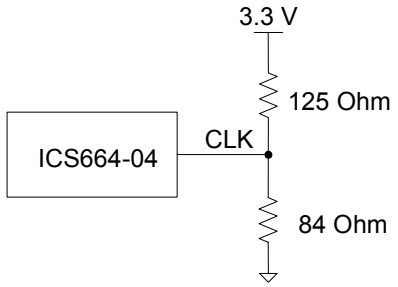
Unless stated otherwise, **VDD =VDDO = 3.3 V ±5%**, Ambient Temperature 0 to +70° C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Crystal Frequency					28	MHz
Output Clock Rise Time	t_{OR}	20% to 80%, C_L=2 pF			1.5	ns
Output Clock Fall Time	t_{OF}	80% to 20%, C_L=2 pF			1.5	ns
Output Duty Cycle	t_{OD}	at VDD/2, C_L=2 pF	40	49 to 51	60	%
Power-up Time	t_{PU}	Inputs out of PD state to clocks stable			10	ms
Power-down Time	t_{PD}	Inputs in PD state to clocks off			1	µs
Peak-to-peak Jitter, Short term				100		ps
Peak-to-peak Jitter, Long term		10 µs delay		400		ps
Single Sideband Phase Noise		10 kHz offset		-100		dBc
Actual Mean Frequency Error versus Target				0		ppm

Thermal Characteristics

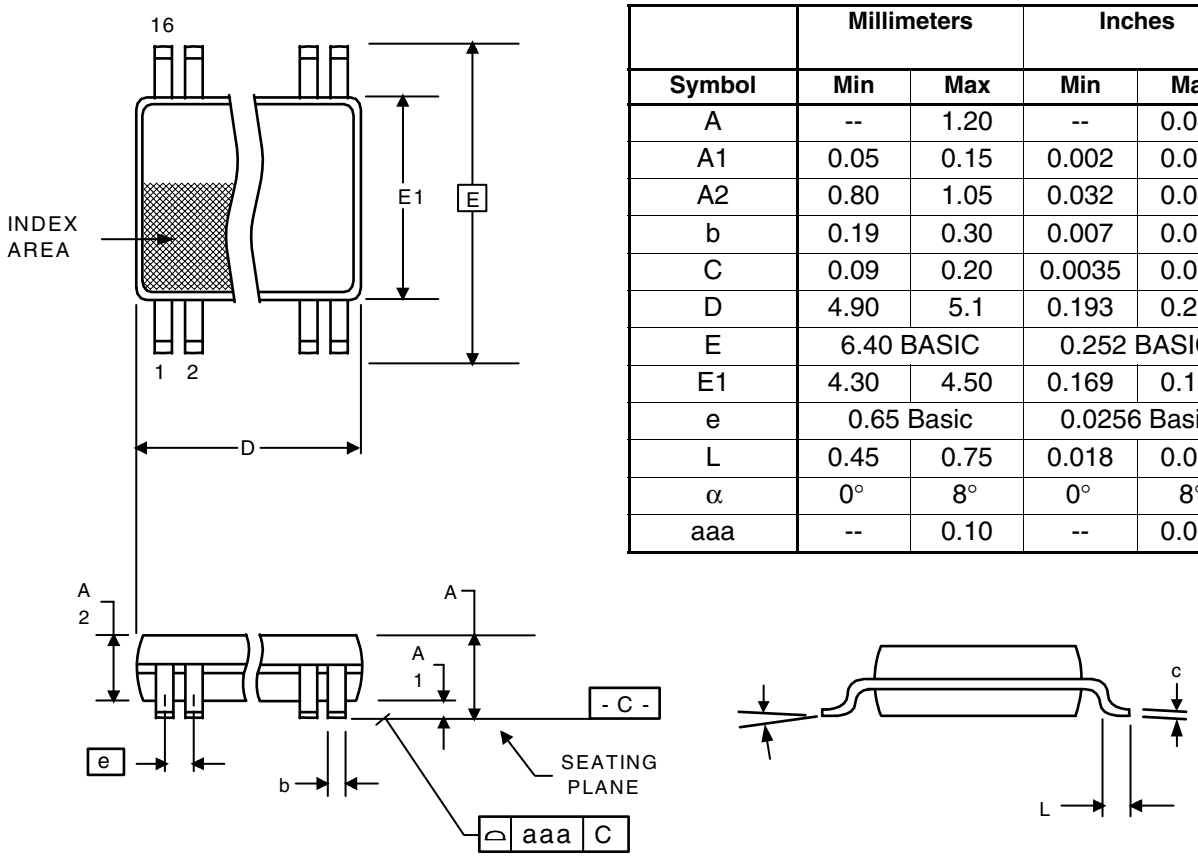
Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Thermal Resistance Junction to Ambient	θ_{JA}	Still air		78		°C/W
	θ_{JA}	1 m/s air flow		70		°C/W
	θ_{JA}	3 m/s air flow		68		°C/W
Thermal Resistance Junction to Case	θ_{JC}			37		°C/W

Typical Output Termination



Package Outline and Package Dimensions (16-pin TSSOP, 4.40 mm Body, 0.65 mm Pitch)

Package dimensions are kept current with JEDEC Publication No. 95, MO-153



	Millimeters		Inches	
Symbol	**Min**	**Max**	**Min**	**Max**
A	--	1.20	--	0.047
A1	0.05	0.15	0.002	0.006
A2	0.80	1.05	0.032	0.041
b	0.19	0.30	0.007	0.012
C	0.09	0.20	0.0035	0.008
D	4.90	5.1	0.193	0.201
E	6.40 BASIC		0.252 BASIC	
E1	4.30	4.50	0.169	0.177
e	0.65 Basic		0.0256 Basic	
L	0.45	0.75	0.018	0.030
α	0°	8°	0°	8°
aaa	--	0.10	--	0.004

Ordering Information

Part / Order Number	Marking	Shipping Packaging	Package	Temperature
664G-04LF	664G04LF	Tubes	16-pin TSSOP	0 to +70° C
664G-04LFTR	664G04LF	Tape and Reel	16-pin TSSOP	0 to +70° C

Parts that are ordered with a "LF" suffix to the part number are the Pb-Free configuration and are RoHS compliant.

Revision History

Rev.	Originator	Date	Description of Change
D		01/23/09	Changed capacitance load rating from 5pF to 2pF.
E	PK	06/05/09	Updated power supply voltage specs; updates to voltage specs on DC char table.

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